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(54) MATERIAL LAYER STACK, LIGHT EMITTING ELEMENT, LIGHT EMITTING PACKAGE, AND METHOD OF FABRICATING LIGHT EMITTING ELEMENT

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(57) ABSTRACT

Disclosed herein are a material layer stack, a light emitting element, a light emitting package, and a method of fabricating a light emitting element. The material layer stack includes: a substrate having a first lattice constant; and a semiconductor layer grown on the substrate, the semiconductor layer having a second lattice constant that is different from the first lattice constant. Using the material layer stack, a light emitting element having a low leakage current, a low operation voltage, and an excellent luminous efficiency can be obtained.

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